

**Amendments to the Claims:**

Claim 16 has been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

**Listing of Claims:**

Claims 1-15. (Canceled)

16. (Currently Amended) A package substrate, comprising:  
a dielectric film having at least one conductive trace disposed upon a top surface thereof, at least one conductive via formed therethrough, and a first longitudinal slot formed therethrough; and  
an electrically conductive layer adhered to the dielectric film and operably coupled to the at least one conductive via, the electrically conductive layer comprising:  
at least one electrical current isolation slot formed therethrough, at least a part of the electrical current isolation slot is coextensive with material of the dielectric film;  
a second longitudinal slot formed through the electrically conductive layer and substantially aligned with the first longitudinal slot in the dielectric film; and  
a surface providing at least one electrical conductor landing area.

17. (Withdrawn) The package substrate of claim 16, further comprising:  
a plurality of discrete conductive elements disposed upon the top surface of the dielectric film bearing the at least one conductive trace, wherein:  
at least one of the plurality of discrete conductive elements is operably coupled to the at least one conductive trace; and  
at least one additional discrete conductive element of the plurality is operably coupled to the at least one conductive via.

18. (Withdrawn) The package substrate of claim 16, wherein the electrically conductive layer includes metal.
19. (Withdrawn) The package substrate of claim 16, wherein the electrically conductive layer is thermally conductive.
20. (Withdrawn) The package substrate of claim 16, wherein the electrically conductive layer provides physical support against torsion and bending of the package substrate.
21. (Withdrawn) The package substrate of claim 16, wherein the electrically conductive layer is configured to be operably coupled to a voltage source selected from the group consisting of a ground voltage reference, a power voltage reference, and an intermediate voltage reference.
22. (Previously Presented) The package substrate of claim 16, wherein the at least one electrical current isolation slot substantially segments the electrically conductive layer into at least two segments wherein high frequency noise present on a voltage source in a first segment of the at least two segments may be substantially isolated from the voltage source in another segment of the at least two segments.
23. (Withdrawn) The package substrate of claim 16, further comprising;  
a longitudinal slot formed through the electrically conductive layer; and  
a longitudinal slot formed through the dielectric film having a slot width wider than the longitudinal slot in the electrically conductive layer such that the at least one electrical conductor landing area is exposed through the longitudinal slot in the dielectric film.
24. (Withdrawn) The package substrate of claim 23, wherein the at least one electrical current isolation slot extends from proximate the longitudinal slot formed through the

electrically conductive layer to proximate a lateral peripheral edge of the electrically conductive layer.

25. (Withdrawn) The package substrate of claim 23, wherein the at least one electrical current isolation slot extends from and is contiguous with the longitudinal slot formed through the electrically conductive layer to proximate a lateral peripheral edge of the electrically conductive layer.

26. (Withdrawn) The package substrate of claim 23, wherein the at least one electrical current isolation slot intersects and extends from a lateral peripheral edge of the electrically conductive layer to proximate the longitudinal slot formed through the electrically conductive layer.

27. (Withdrawn) The package substrate of claim 16, wherein the dielectric film further comprises a multilayer film having at least one additional layer of conductive traces, at least one additional dielectric layer and at least one interlayer conductive via effecting connection between the at least one conductive trace and a conductive trace of the at least one additional layer of conductive traces.

Claims 28-36. (Canceled)